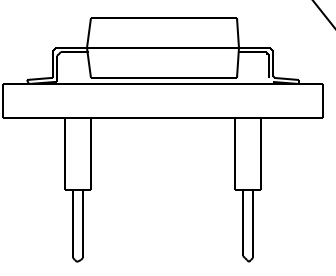
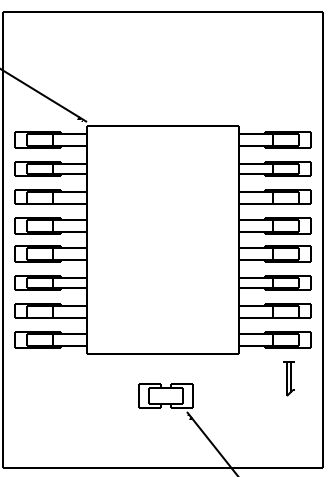
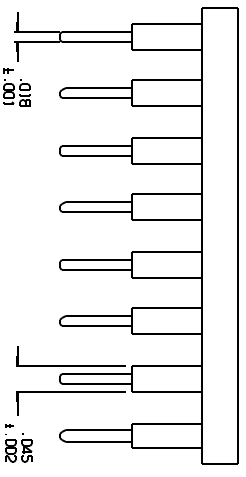
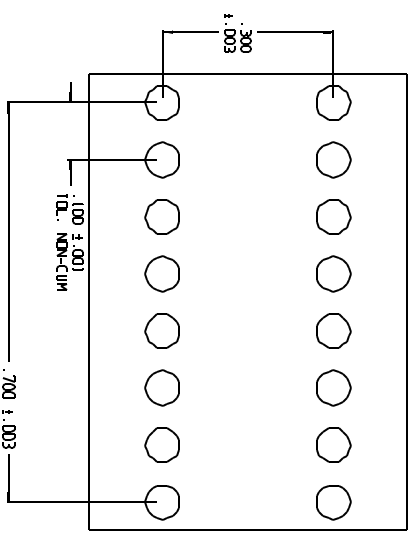
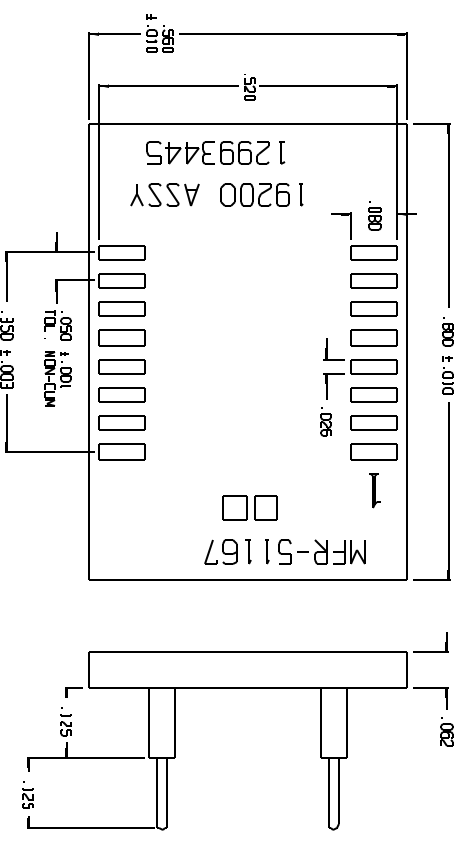


DRAWING NO.		
7750-122-18-B		
REV:	ECN NO.	DATE:
1	PRELIM.	7/21/05
APP:	JW	



NOTE:
 1. BOARD MATERIAL: .062 FR-4 PER IPC-4101/21
 2. PIN MATERIAL: BRASS ALLOY 360, 1/2 HARD PER ASTM-B121.
 3. PIN PLATING: 200U" MIN. TIN/LEAD PER ASTM B545 OVER 100U" MIN. NICKEL PER SAE AMS-DD-N-290.

INCH (MM)	DR INCH (MM)	TOLERANCES UNLESS OTHERWISE SPECIFIED	MATL: SEE NOTES
		± .03	USED ON:
		± .015	DES: JAH 7/21/05
		± .005	CKD:
		± 2°	APP:
THIRD ANGLE PROJECTION		MOLD NO.	

ARIES ELECTRONICS, INC.
 FRENCHTOWN, N. J. 08825

SCALE:	1:1	TITLE:	16 PIN FORMED LEAD FLAT PACK
SHEET 1 OF 1		TD	16 PIN DIP CAC
SIZE	AS	DRAWING NO.	7750-122-18-B
REV	2		